

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1728684	wire wiring damascene metalliz\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:53
L2	23138	(third multiple multi) adj (insulat\$4 dielectric oxide nitride low-dielectric\$ low adj dielectric low adj k low-k hsq (hydrogen methylat\$4) adj2 silsesquioxane msq methylsilsesquioxane mhsq silk sog spin adj on adj glass fox flow\$4 adj oxide parylene cytop bcp benzocyclobutene)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:34
L3	3693944	airgap gap pocket aperature opening	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:35
L4	5193781	airgap gap pocket aperature opening space	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:23
L5	629	1 same 2 same 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:23
L6	296	1 with 2 with 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:24
L7	253	6 and (@ad < "20030117")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:36
L8	4677764	gap aperature opening trench channel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:34

L9	86734	(second! additional\$4 another) adj (insulat\$4 dielectric oxide nitride low-dielectric\$ low adj dielectric low adj k low-k hsq (hydrogen methylat\$4) adj2 silsesquioxane msq methylsilsesquioxane mhsq silk sog spin adj on adj glass fox flow\$4 adj oxide parylene cytop bcp benzocyclobutene)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:35
L10	9998	9 near4 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:35
L11	1037105	airgap gap	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:35
L12	550	2 with 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:36
L13	221	10 and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:36
L14	167	13 and (@ad < "20030117")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:42
L15	1773695	capacit\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:36
L16	97735	15 with 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 20:39
L17	47	14 and 16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:42

L18	153	siof near2 (low adj k low-k low adj dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:42
L19	132	18 and (@ad < "20030117")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:39
L20	2	"6064118".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:47
L21	0	20 and (resin epoxy encapsul\$6 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:47
L22	2851177	(resin epoxy encapsul\$6 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:48
L23	32	18 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:49
L24	71370	(resin epoxy) with (packag\$4 encapsul\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:43
L25	0	18 and 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:49
L26	14	18 and (resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:53
L27	19	18 and (packag\$4 encapsulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:38

L28	25764	1 and 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:43
L29	71	18 and (@ay < "2000")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:39
L30	1748	28 and (@ay = "2000")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:43
L31	2253	(resin epoxy) near2 (insulat\$4 dielectric\$4) with (packag\$4 encapsul\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:43
L32	1462	1 and 31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:43
L33	92	32 and (@ay = "2000")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 22:44
L34	5381	((438/622) or (438/631) or (438/637) or (438/675)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 23:11